

FIG. 1

108090" 2019/06/00

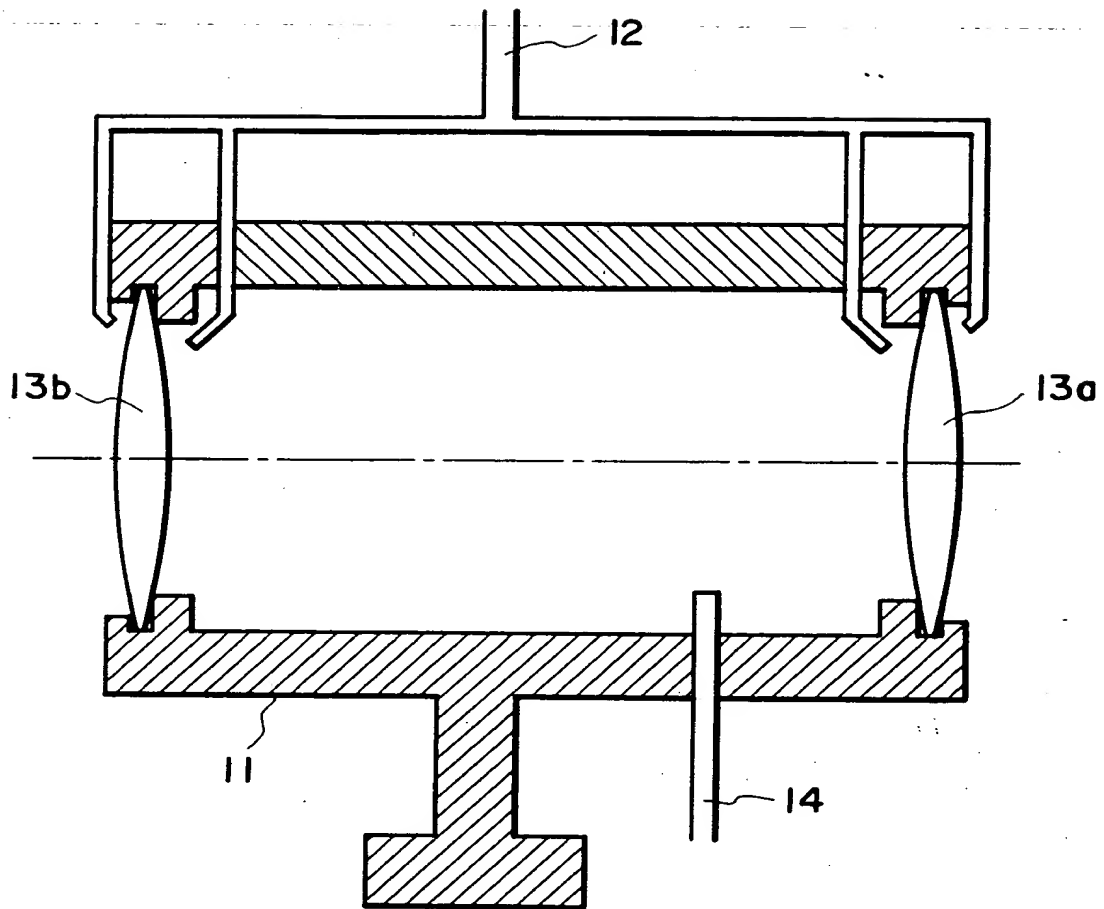


FIG. 2

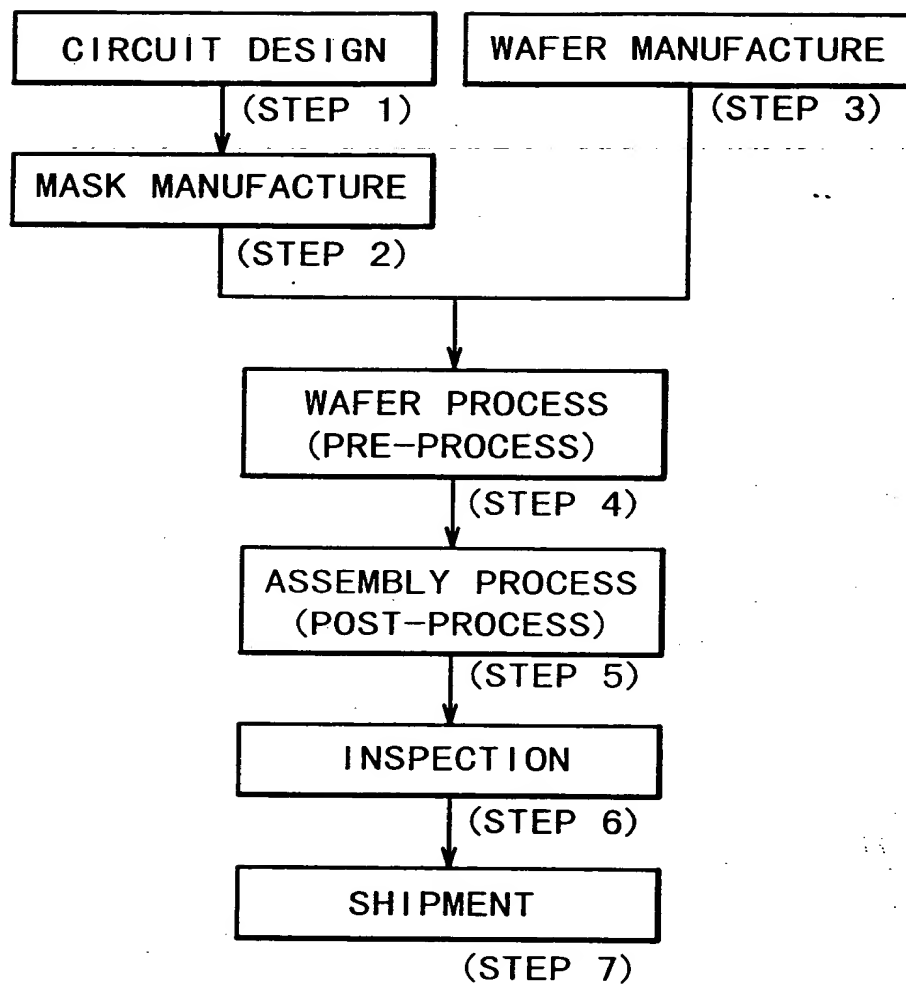


FIG. 3

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graph TD; A[OXIDATION  
(STEP 11)] --> B[C V D  
(STEP 12)]; B --> C[ELECTRODE  
FORMATION  
(STEP 13)]; C --> D[ION IMPLANTAION  
(STEP 14)]; D --> E[RESIST PROCESS  
(STEP 15)]; E --> F[EXPOSURE  
(STEP 16)]; F --> G[DEVELOPMENT  
(STEP 17)]; G --> H[ETCHING  
(STEP 18)]; H --> I[RESIST  
SEPARATION  
(STEP 19)]; I -- REPEAT --> A;
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The flowchart illustrates a semiconductor manufacturing process. It begins with a vertical sequence of four steps: OXIDATION (STEP 11), C V D (STEP 12), ELECTRODE FORMATION (STEP 13), and ION IMPLANTAION (STEP 14). An arrow from the right side of the ION IMPLANTAION box leads to the RESIST PROCESS (STEP 15) box, which starts a second vertical sequence of steps: EXPOSURE (STEP 16), DEVELOPMENT (STEP 17), ETCHING (STEP 18), and RESIST SEPARATION (STEP 19). A feedback loop labeled "REPEAT" connects the bottom of the RESIST SEPARATION box back to the input of the OXIDATION box.

FIG. 4